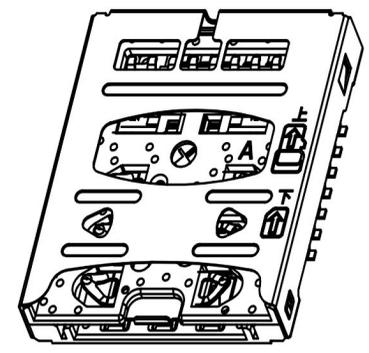
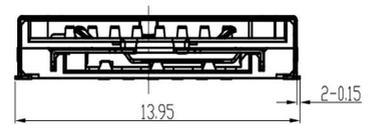
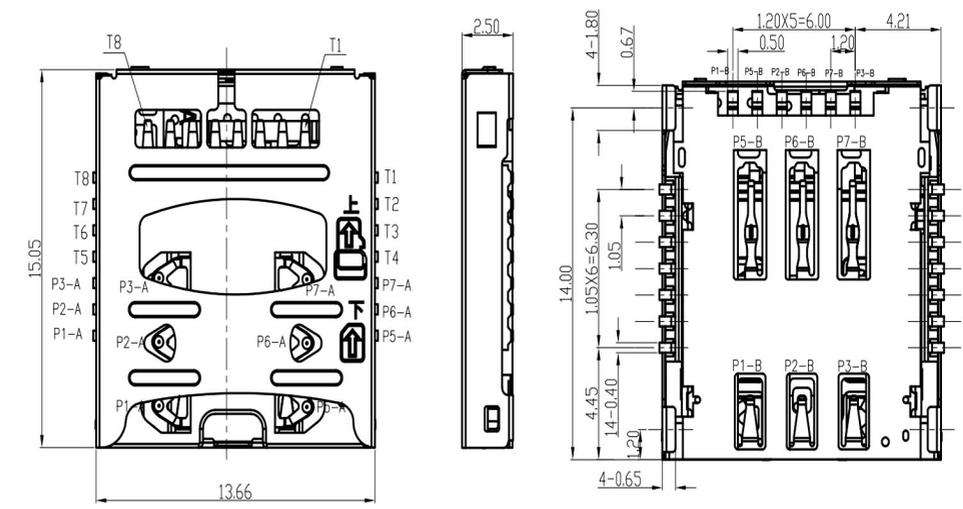


1 2 3 4 5 6 7 8

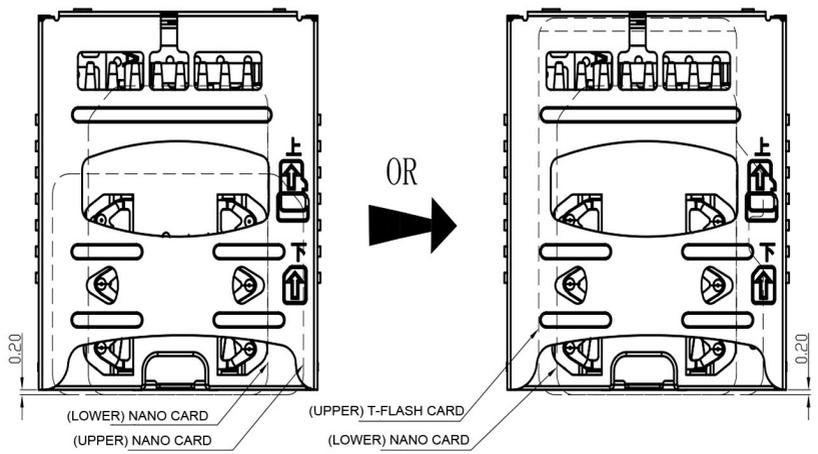
A  
B  
C  
D  
E  
F  
G  
H

A  
B  
C  
D  
E  
F  
G  
H



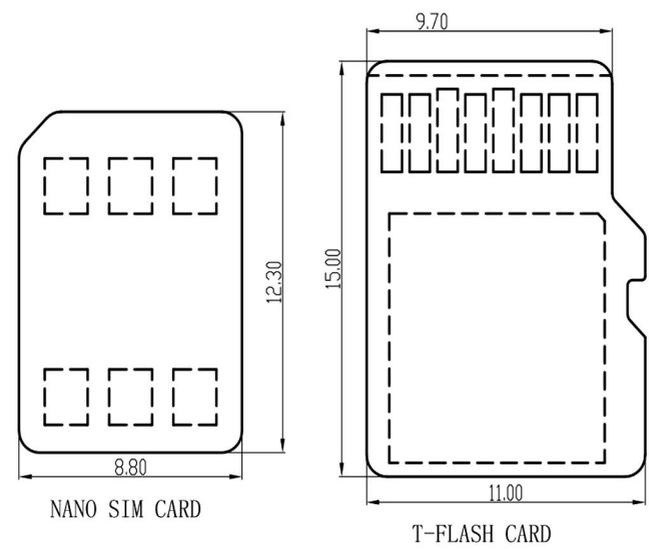
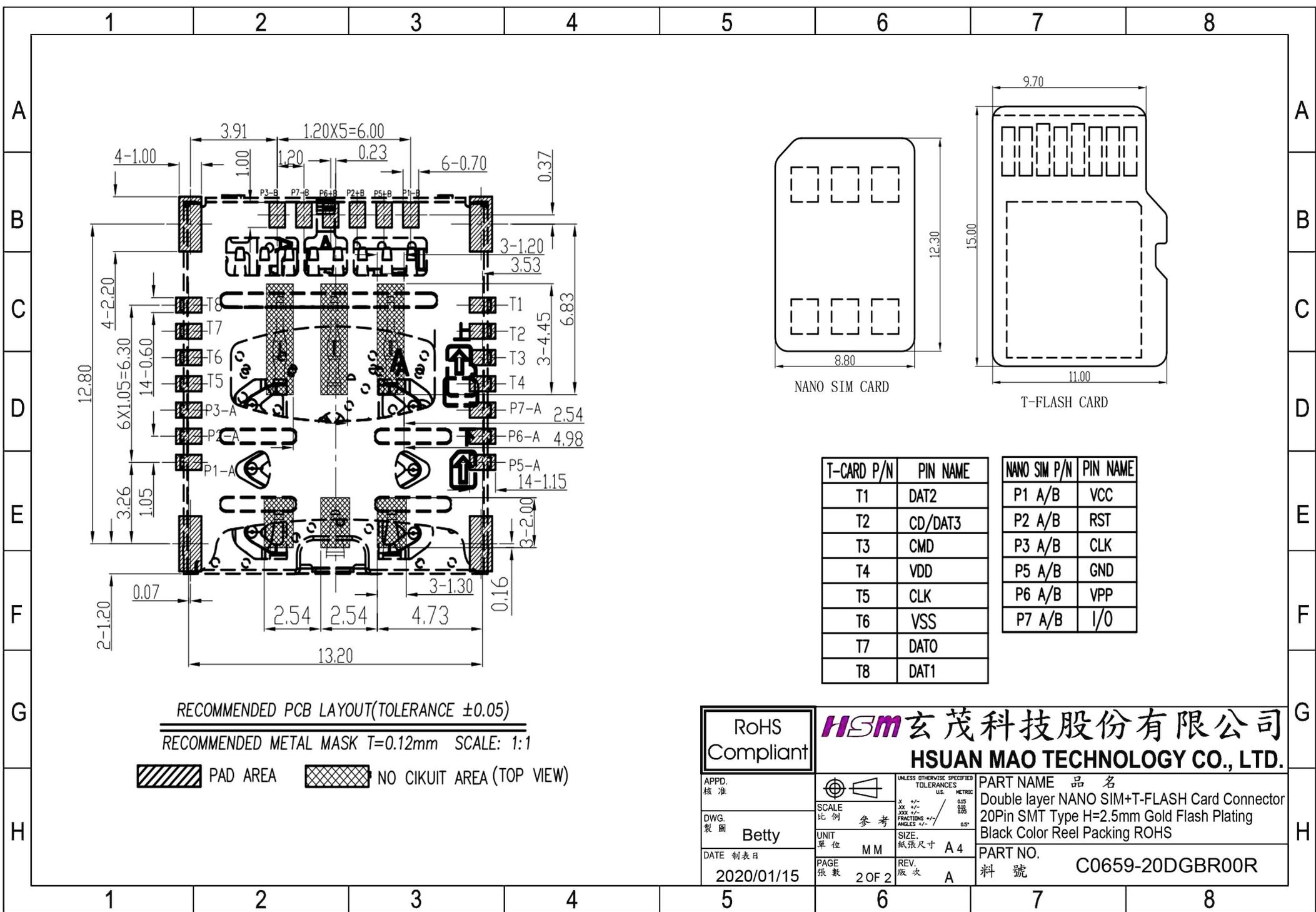
NOTES:

1. MATERIAL:
  - HOUSING: Thermoplastic,UL 94-V02.
  - TERMINAL: Copper alloy.
  - SHELL: Stainless steel.
- 2.FINISH:
  - TERMINAL: Ni under-plated and Au plated on contact areas,G/F plated on solder tails;
  - SHELL: Ni under-plated and G/F plated on solder tails.
- 3.SPECIALITY:
  - Rated current:1.0A
  - Rated voltage:30V
  - Contact Resistance:60m Ohms MAX.
  - Insulation Resistance:1000M Ohms MIN. 500V DC
  - Dielectric withstanding voltage: 500V DC.
  - Solderability:250±5°C, 10±0.5s.
  - Durability:3,000 Cycles
  - Operating Temperature:-25°C~+70°C.



RoHS Compliant		<b>HSM</b> 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.	
APPD. 核准		UNLESS OTHERWISE SPECIFIED TOLERANCES	PART NAME 品名
DWG. 製圖	Betty	SCALE 比例 參考	Double layer NANO SIM+T-FLASH Card Connector
DATE 制表日	2020/01/15	UNIT 單位 M M	20Pin SMT Type H=2.5mm Gold Flash Plating
		PAGE 張數 1 OF 2	Black Color Reel Packing ROHS
		REV. 版次 A	PART NO. 料號 C0659-20DGBR00R

1 2 3 4 5 6 7 8



T-CARD P/N	PIN NAME
T1	DAT2
T2	CD/DAT3
T3	CMD
T4	VDD
T5	CLK
T6	VSS
T7	DAT0
T8	DAT1

NANO SIM P/N	PIN NAME
P1 A/B	VCC
P2 A/B	RST
P3 A/B	CLK
P5 A/B	GND
P6 A/B	VPP
P7 A/B	I/O

RECOMMENDED PCB LAYOUT(TOLERANCE ±0.05)  
 RECOMMENDED METAL MASK T=0.12mm SCALE: 1:1

PAD AREA    NO CIKUIT AREA (TOP VIEW)

RoHS Compliant		玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.	
APPD. 核准 Betty	SCALE 比例 参考 UNIT 單位 M M PAGE 張數 2 OF 2	UNLESS OTHERWISE SPECIFIED TOLERANCES US. METRIC X +/- .015 .125 XX +/- .010 .075 XXX +/- .0075 .050 ANGLES +/- .05°	PART NAME 品名 Double layer NANO SIM+T-FLASH Card Connector 20Pin SMT Type H=2.5mm Gold Flash Plating Black Color Reel Packing ROHS PART NO. 料號 C0659-20DGBR00R
DATE 制表日 2020/01/15		REV. 次 A	